FM0+64SD1NQ

1. Power supply selection (Note: * default setting)

POWER SOURCE

	CN28	CN33	CN35
DC 5V	1-2*	1-2*	1-2*
USB VBUS	1-2	1-2	2-3
JTAG V-supply	1-2	2-3	Open

VCC SELECTION

	CN36	CN37	CN38	CN39
3.3V	1-2*	1-2*	1-2*	1-2*
5V	2-3	2-3	1-2	1-2

2. Switch, Jumper Pin Settings (Note: * default setting)

	FUNCTION	SETTING	ACTION
SW1	RESET SWITCH	PUSH ON	RESET
		PUSH OFF	NOT RESET
SW2	MD0	1-2	HIGH
		2-3*	LOW
SW3	MD1	1-2	HIGH
		2-3*	LOW
SW4	USB SELECTION	5-6 2-3	USB HOST
		4-5 1-2*	USB FUNC
SW5	WKUP LEVEL SWITCH	5-6 2-3	H ENABLE
		4-5 1-2*	L ENABLE
SW6	(NO MOUNT)	-	-
SW7	(OPTIONAL)	-	-
SW8	(OPTIONAL)	-	-
CN1	AVRH	1-2*	CONNECT TO AVCC
CN2	AVRL	1-2*	CONNECT TO AVSS
CN11	INITX	1-2*	CONNECT TO RESET SWITCH
		2-3	OPEN
CN12	SOT (UART TX)	1-2*	OPEN
		2-3	CONNECT TO RS TRANSCEIVER
		3-4	CONNECT TO SWD I/F (SWCLK)

CN13	MD0	1-2*	CONNECT TO MD0 SWITCH
		2-3	OPEN
CN15	SIN (UART RX)	1-2*	OPEN
		2-3	CONNECT TO RS TRANSCEIVER
		3-4	CONNECT TO SWD I/F (SWDIO)
CN16	MD1	1-2*	CONNECT TO MD1 SWITCH
		2-3	OPEN
CN17	UDP0 (USB D+)	1-2*	OPEN
		2-3	CONNECT TO USB CONNECTOR
CN19	UDM0 (USB D-)	1-2*	OPEN
		2-3	CONNECT TO USB CONNECTOR
CN20	P50	1-2*	OPEN
		2-3	CONNECT TO VBUS CONTROL IC FLG
CN21	P22 (USB-PLL)	1-2*	OPEN
		2-3	USB PLL OFF
		3-4	USB PLL ON
CN22	P51	1-2*	OPEN
		2-3	CONNECT TO VBUS CONTROL IC EN
CN23	P61	1-2*	OPEN
		2-3	CONNECT TO USB D+ PULL-UP CONTROL
CN25	P60 (USB CONN. DET.)	1-2*	OPEN
		2-3	CONNECT TO USB VBUS
CN26	P0F	1-2*	DO NOT USE WKUP SW (SW6)
		2-3	USE WKUP SW (SW6)
CN27	TEST CONNECTOR	1-2*	DO NOT USE USB
		2-3	USE USB
CN29	SWCLK	1-2*	OPEN
		2-3	PULL-DOWN
		3-4	PULL-UP
CN30	SWDIO	1-2*	OPEN
		2-3	PULL-UP

Revision history:
2015/3/25 Initial revision

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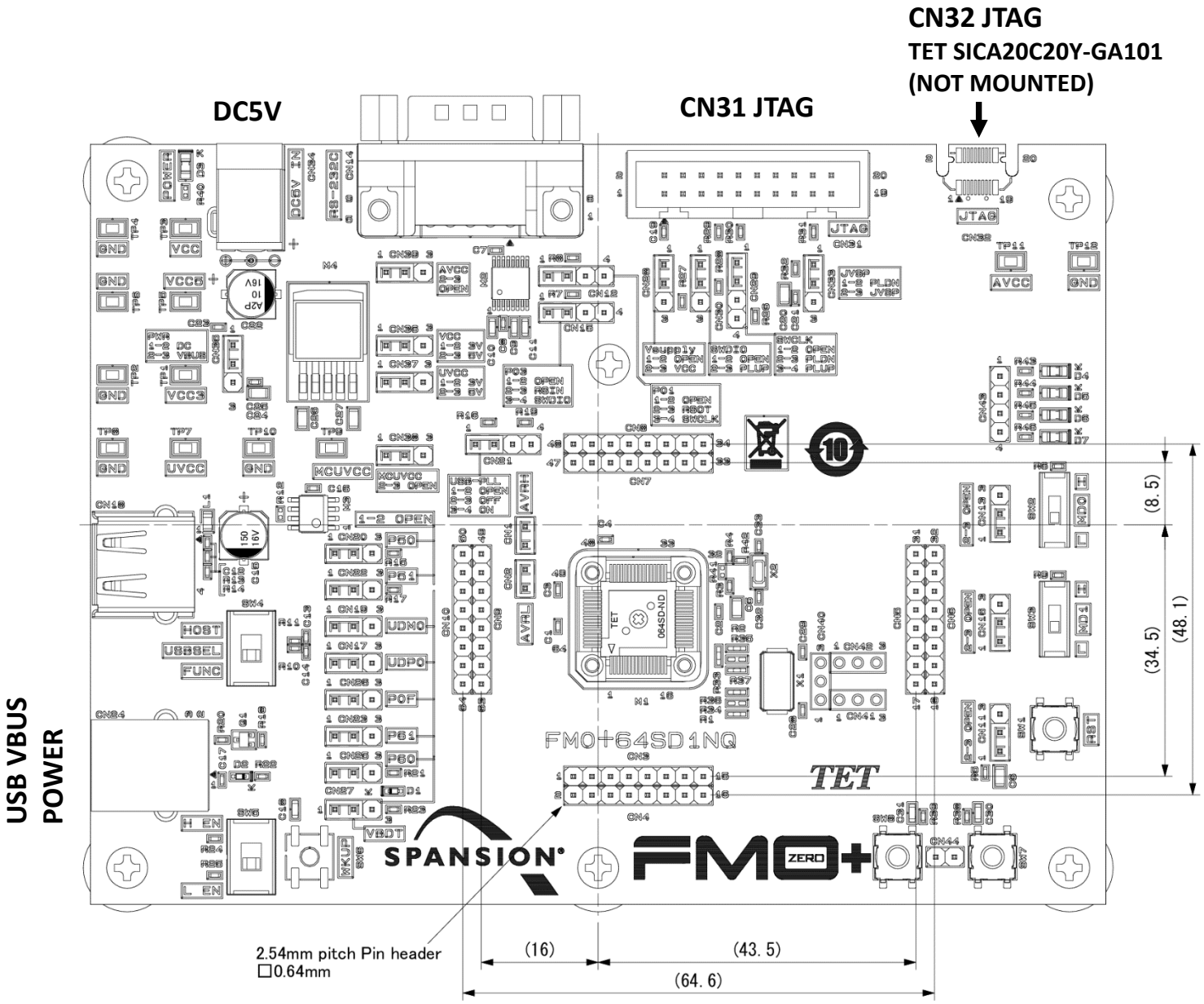
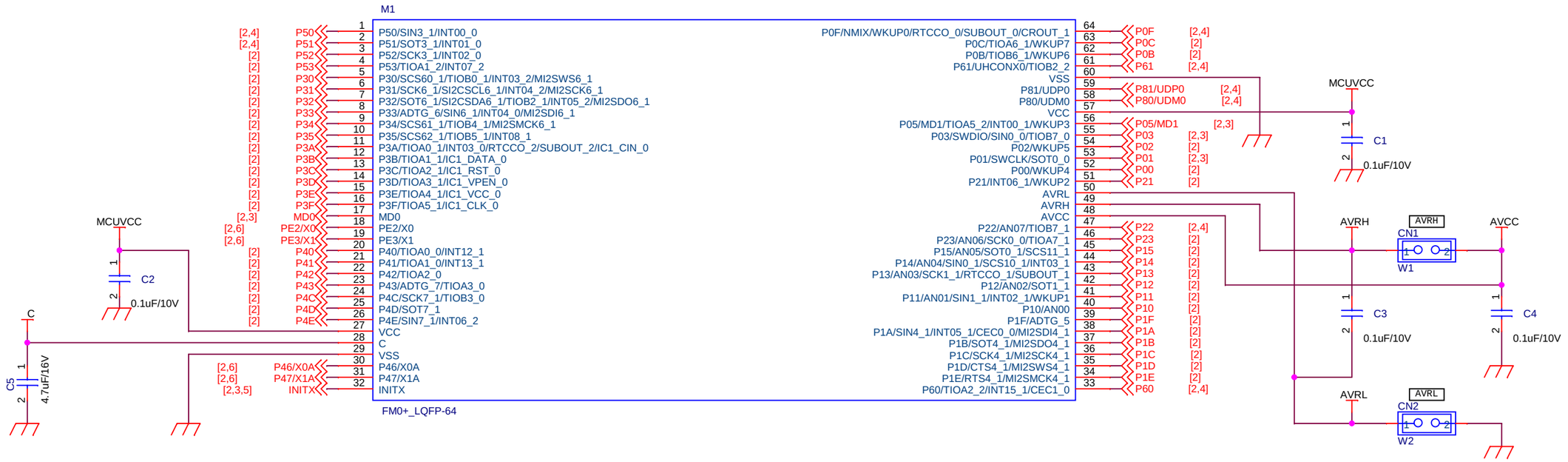
The following precautions apply to the product described in this manual.

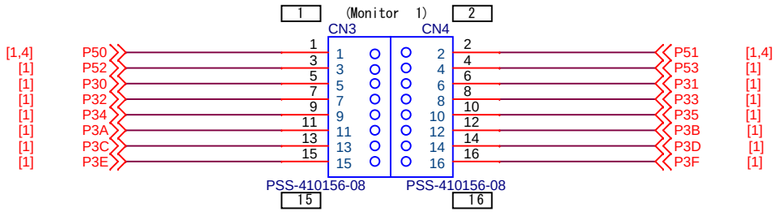
Before moving the product, be sure to turn off all the power supplies and unplug the cables. Watch your step when carrying the product. Do not use the product in an unstable location such as a place exposed to strong vibration or a sloping surface.
Do not place anything on the product or expose the product to physical shocks. Do not carry the product after the power has been turned on. Doing so may cause a malfunction due to overloading or shock.
Since the product contains many electronic components, keep it away from direct sunlight, high temperature, and high humidity to prevent condensation. Do not use or store the product where it is exposed to much dust or a strong magnetic or electric field for an extended period of time. Inappropriate operating or storage environments may cause a fault.
Use the product within the ranges given in the specifications. Operation over the specified ranges may cause a fault.
To prevent electrostatic breakdown, do not let your finger or other object come into contact with the metal parts of any of the connectors. Before handling the product, touch a metal object (such as a door knob) to discharge any static electricity from your body.
Always turn the power off before connecting or disconnecting any cables from the product. When unplugging a cable, unplug the cable by holding the connector part without pulling on the cable itself. Pulling the cable itself or bending it may expose or disconnect the cable core, resulting in a fault.
It is recommended that it be stored in the original packaging. Transporting the product may cause a damage or fault. Therefore, keep the packaging materials and use them when re-shipping the product.

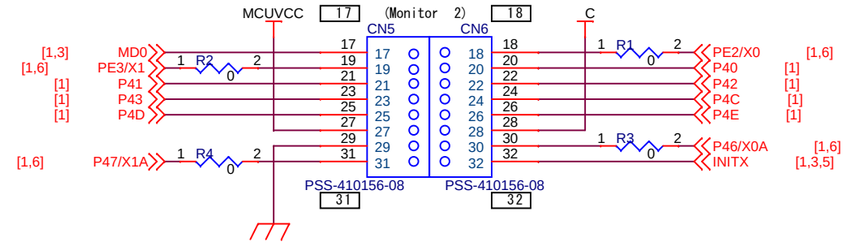
FM0+64SD1NQ (FIGURE EXAMPLE BELOW)

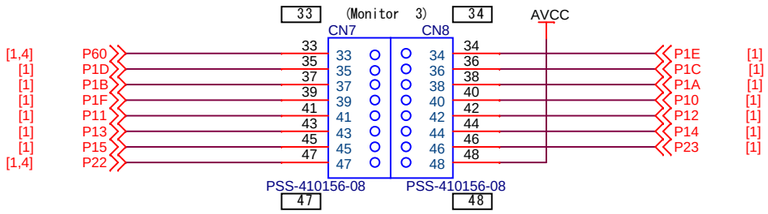


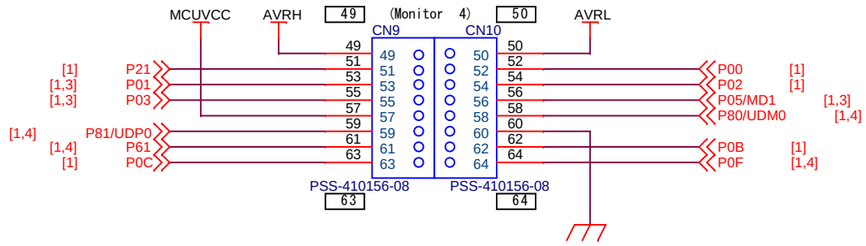


						Title	FM0+ Evaluation Board (LQFP-64) MCU or SOCKET
						Draw.No.	
Ed.	Date	Desig.	Check	Appr.	Description		
Desig.			Check		Appr.	Spansion Inc.	Sheet 1 / 6









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Title
FM0+ Evaluation Board (LQFP-64)
Monitor Pins

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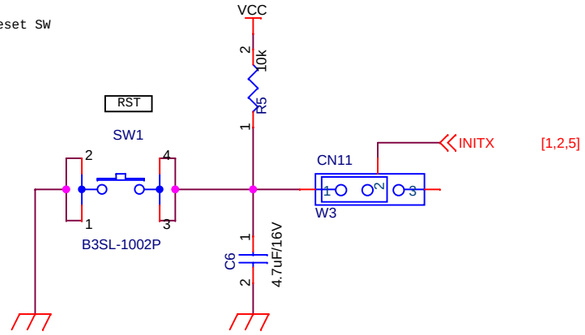
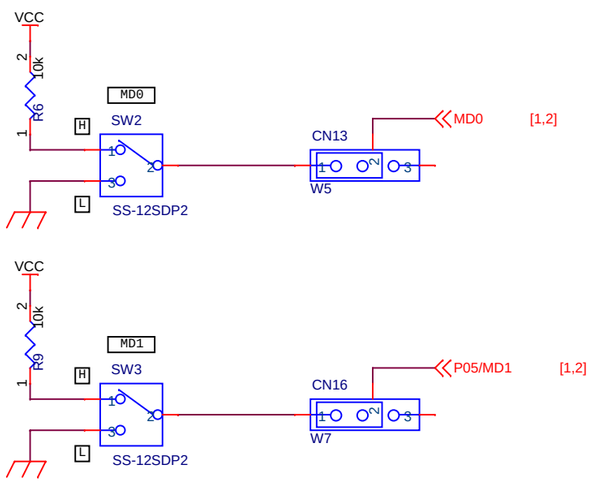
Sheet 2 / 6

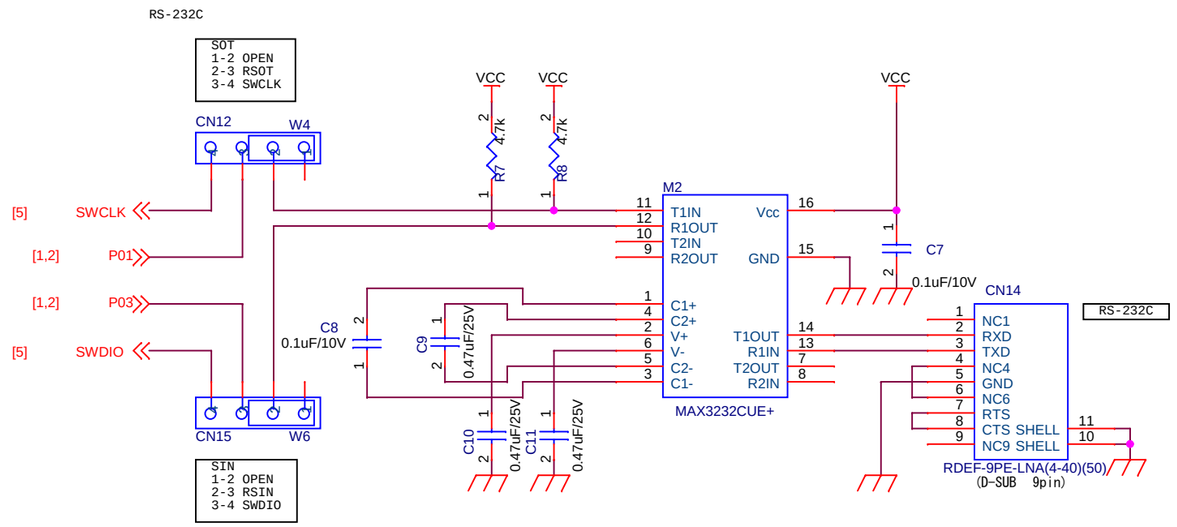
Reset SW



MODE SW



RS-232C



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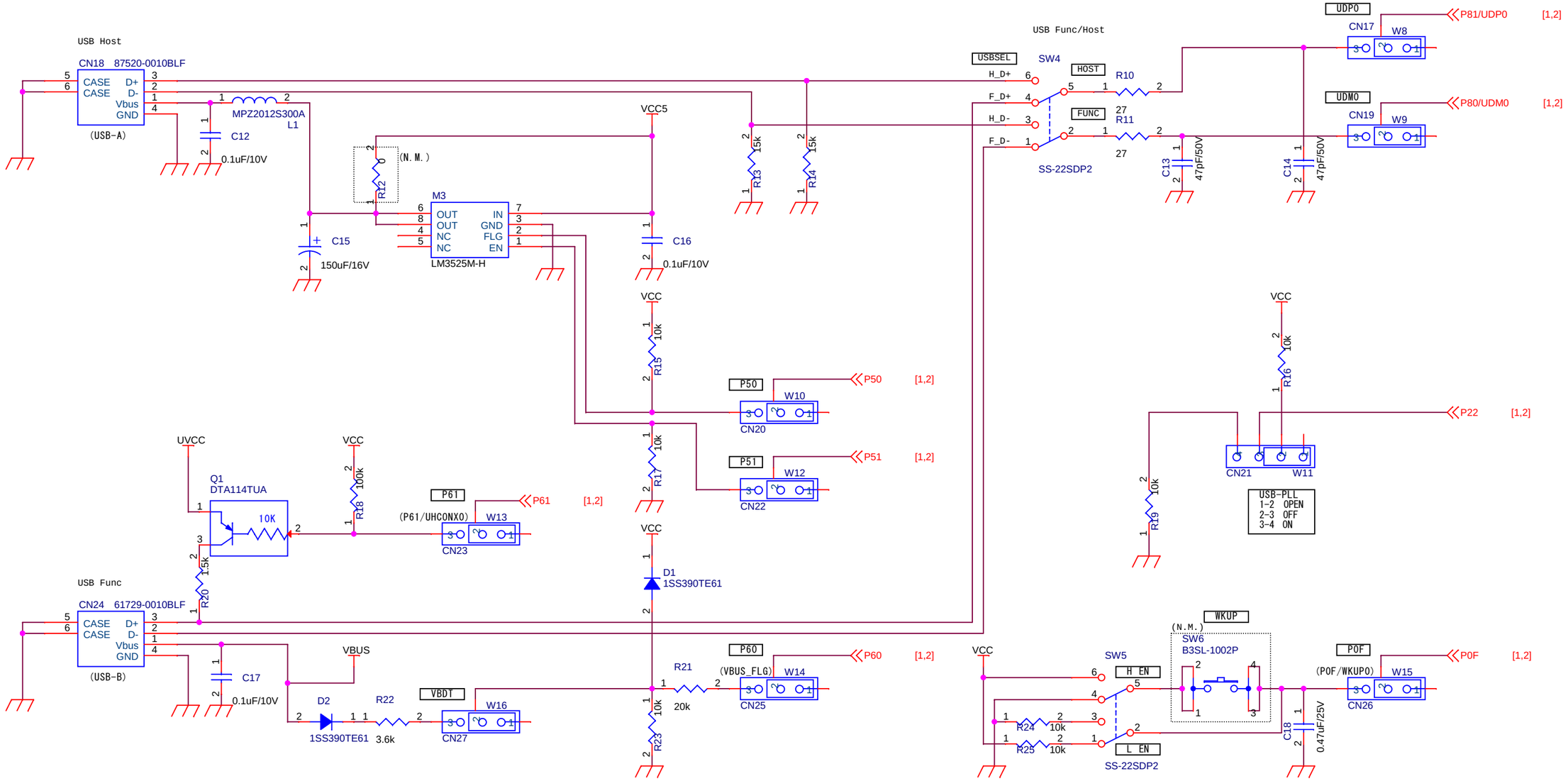
Title
FM0+ Evaluation Board (LQFP-64)
MODE, RESET, RS232C

Draw.No.

Spansion Inc.

Sheet 3 / 6



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								Draw.No.	
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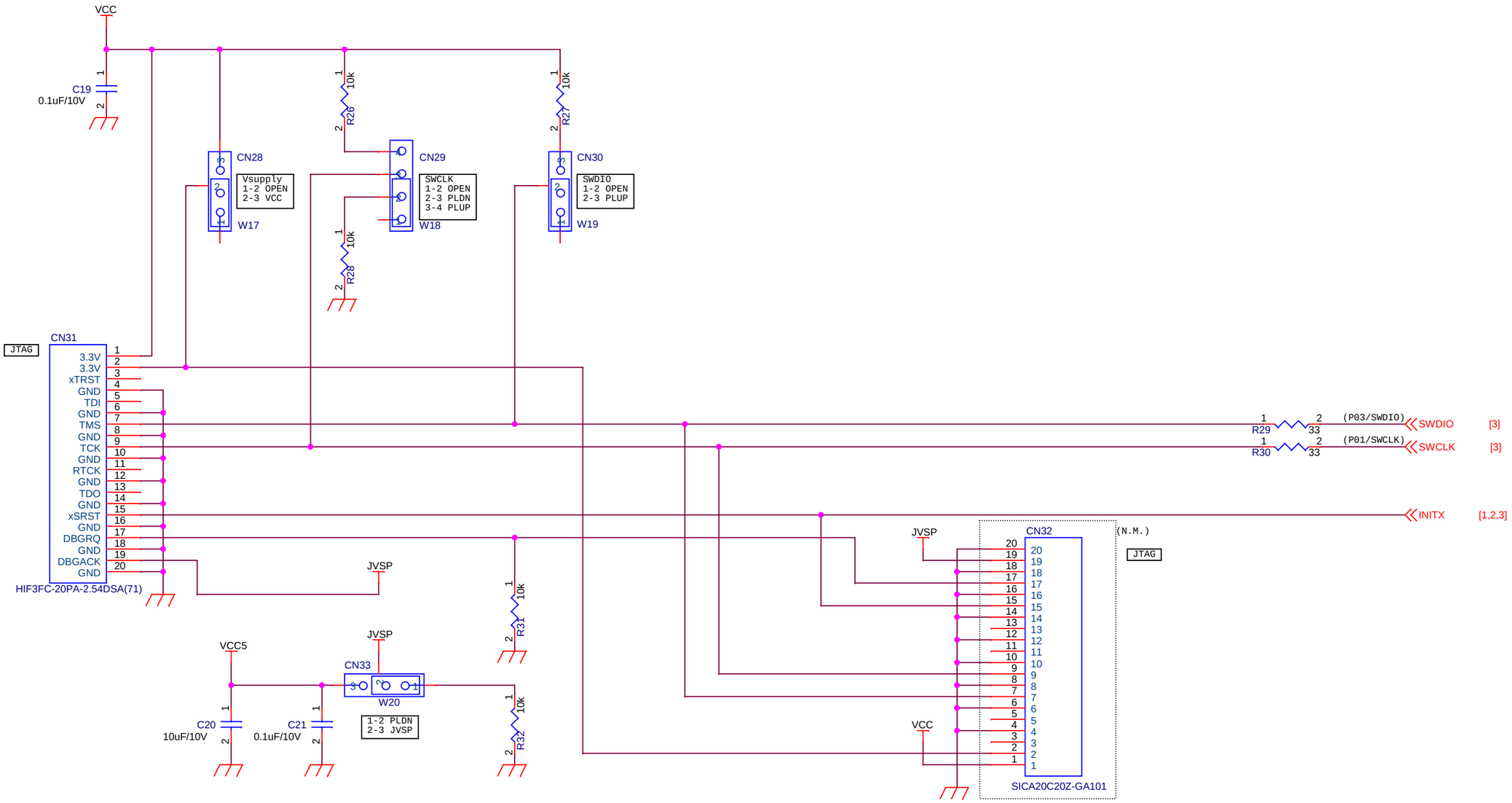
JTAG



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								Draw.No.	
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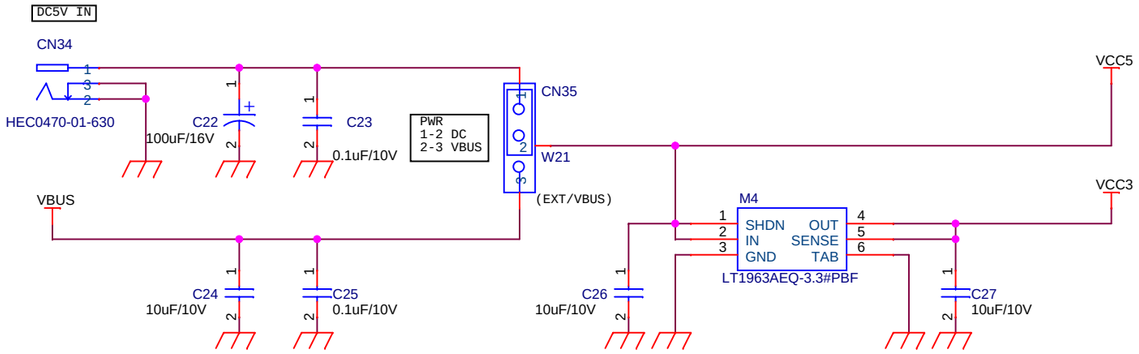
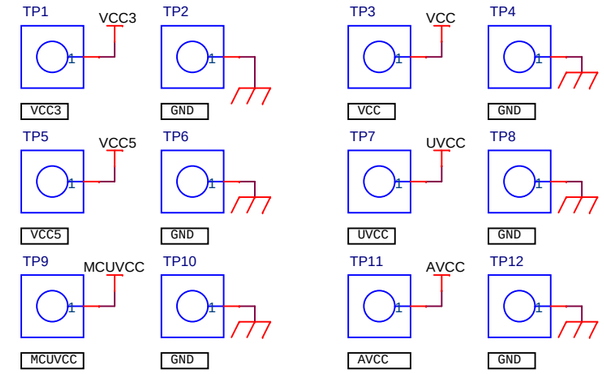
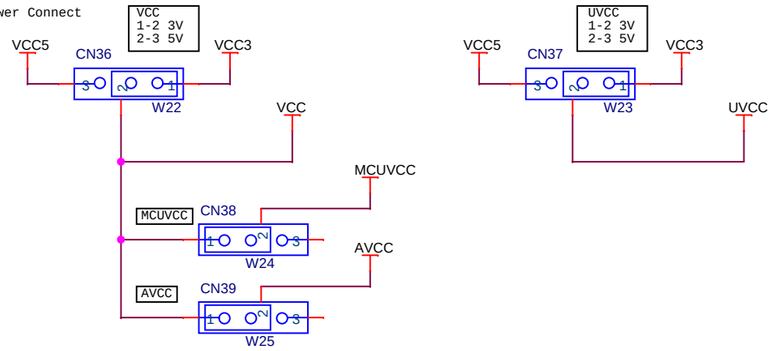
Power



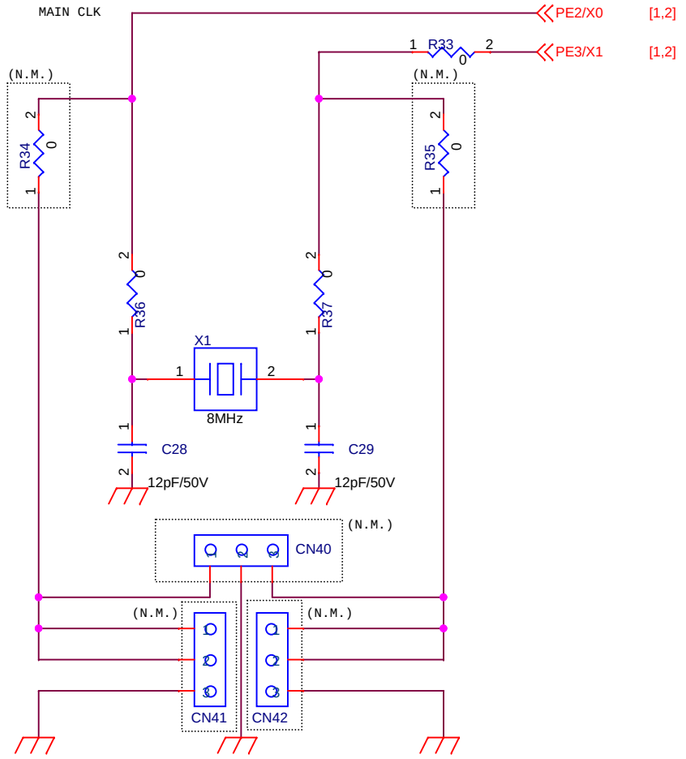
Power Pin



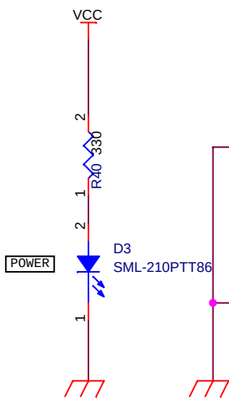
Power Connect



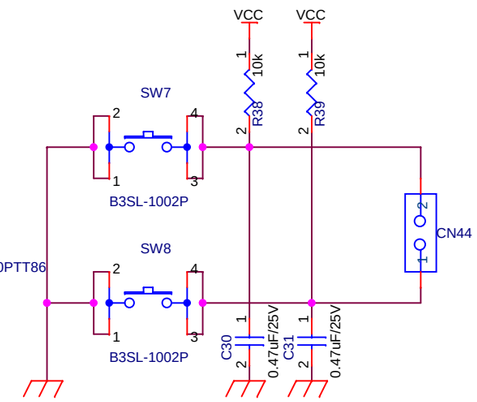
MAIN CLK



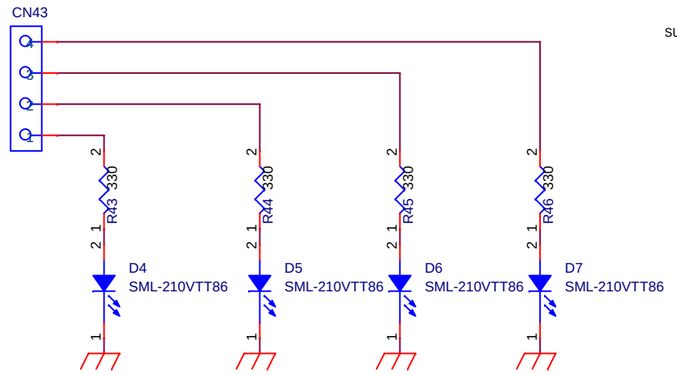
Power LED



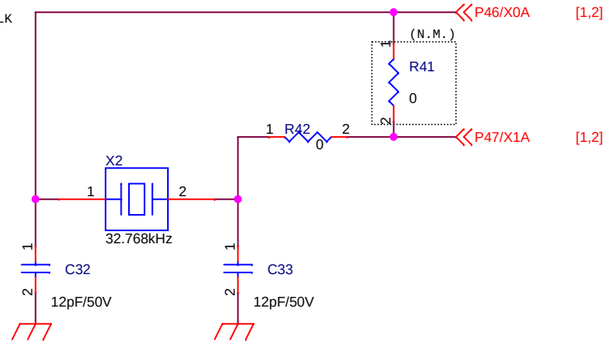
Push SW



LED



SUB CLK



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Title
FM0+ Evaluation Board (LQFP-64)
POWER, LED, SWITCH, CLOCK

Draw.No.

Spansion Inc.

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FM0+64SD1NQ

Rev.01

中華人民共和国「電子情報製品汚染防止管理弁法」の対応

Compliance with Administration on the Control of Pollution Caused by Electronic Information Products of the People's Republic of China

电子信息产品污染控制管理办法（第 39 号）

这标记是按照 2006 年 2 月 28 日公布的[电子信息产品污染控制管理办法]以及 SJ/T11364-2006[电子信息产品污染控制标识要求]在中国销售的电子信息产品的环保使用期限。如遵守关于这产品的安全或使用上的注意，在这期限内（从生产日期起算）不会因产品中的有害物质漏到外部，或发生突然变异，而引起环境污染和对人体或财产的重大影响。

产品中有毒有害物质或元素的名称及含量

部件名称	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr(VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
印刷线路板	×	○	○	○	○	○

○：表示该有毒有害物质在该部件所有均质材料中的含量均在 SJ/T11363-2006 规定的限量要求以下。
×：表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T11363-2006 规定的限量要求。

2015/3/25